



7A, 650V N-CHANNEL MOSFET

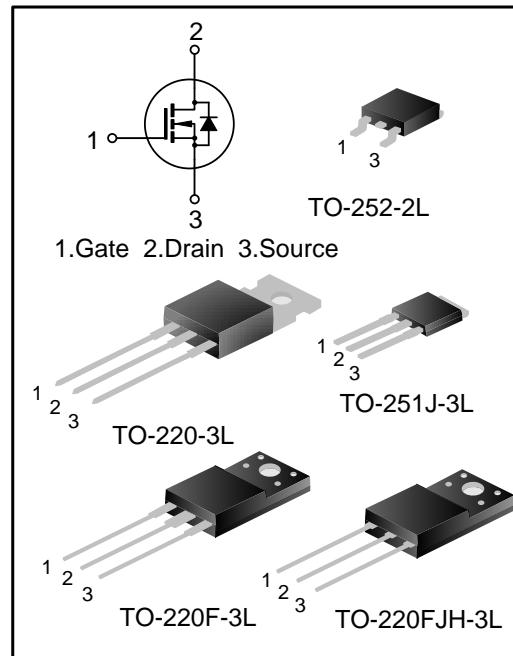
GENERAL DESCRIPTION

SVF7N65RD(MJ)(FJH)(F)(T) is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ structure VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- 7A, 650V, $R_{DS(on)(typ.)}=1.2\Omega @ V_{GS}=10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVF7N65RMJ	TO-251J-3L	7N65RMJ	Halogen free	Tube
SVF7N65RDTR	TO-252-2L	7N65RD	Halogen free	Tape&Reel
SVF7N65RFJH	TO-220FJH-3L	7N65RFJH	Halogen free	Tube
SVF7N65RF	TO-220F-3L	SVF7N65RF	Halogen free	Tube
SVF7N65RT	TO-220-3L	SVF7N65RT	Halogen free	Tube



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SVF7N65RD(MJ)(FJH)(F)(T)_Datasheet

ABSOLUTE MAXIMUM RATINGS (T_c=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Ratings			Unit	
		SVF7N65 RD/MJ	SVF7N65 RFJH/F	SVF7N65 RT		
Drain-Source Voltage	V _{DS}	650		V		
Gate-Source Voltage	V _{GS}	±30		V		
Drain Current	T _c = 25°C	I _D	7.0		A	
	T _c = 100°C		4.4			
Drain Current Pulsed	I _{DM}	28		A		
Power Dissipation(T _c =25°C) -Derate above 25°C	P _D	90	46	145	W	
		0.72	0.31	1.16	W/°C	
Single Pulsed Avalanche Energy (Note 1)	E _{AS}	317		mJ		
Reverse diode dv/dt (Note 2)	dv/dt	4.5		V/ns		
MOSFET dv/dt ruggedness (Note 3)	dv/dt	50		V/ns		
Operation Junction Temperature Range	T _J	-55~+150		°C		
Storage Temperature Range	T _{stg}	-55~+150		°C		

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings			Unit
		SVF7N65 RD/MJ	SVF7N65 RFJH/F	SVF7N65 RT	
Thermal Resistance, Junction-to-Case	R _{θJC}	1.39	2.7	0.86	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.0	62.5	62.5	°C/W

ELECTRICAL CHARACTERISTICS ($T_c=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	650	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2.0	--	4.0	V
Gate resistance	R_g	$f=1.0\text{MHz}$	--	3.2	--	Ω
Static Drain- Source On State Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.5\text{A}$	--	1.2	1.4	Ω
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	--	895	--	pF
Output Capacitance	C_{oss}		--	88	--	
Reverse Transfer Capacitance	C_{rss}		--	7.5	--	
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=325\text{V}, R_{\text{G}}=25\Omega, I_{\text{D}}=7.0\text{A}$ (注 4, 5)	--	14	--	ns
Turn-on Rise Time	t_r		--	33	--	
Turn-off Delay Time	$t_{\text{d(off)}}$		--	58	--	
Turn-off Fall Time	t_f		--	36	--	
Total Gate Charge	Q_g	$V_{\text{DS}}=520\text{V}, I_{\text{D}}=7.0\text{A}, V_{\text{GS}}=10\text{V}$ (注 4, 5)	--	24	--	nC
Gate-Source Charge	Q_{gs}		--	6.0	--	
Gate-Drain Charge	Q_{gd}		--	11	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	Integral Reverse P-N Junction Diode in the MOSFET	--	--	7.0	A
Pulsed Source Current	I_{SM}		--	--	28	
Diode Forward Voltage	V_{SD}	$I_s=7.0\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_s=7.0\text{A}, V_{\text{GS}}=0\text{V},$ $dI/dt=100\text{A}/\mu\text{s}$ (Note 4)	--	566	--	ns
Reverse Recovery Charge	Q_{rr}		--	3.2	--	

Notes:

1. $L=30\text{mH}, I_{\text{AS}}=4.3\text{A}, V_{\text{DD}}=100\text{V}, R_{\text{G}}=25\Omega$, starting $T_j=25^\circ\text{C}$;
2. $V_{\text{DS}}=0\sim 400\text{V}, I_{\text{SD}} \leq 7\text{A}, T_j=25^\circ\text{C}$;
3. $V_{\text{DS}}=0\sim 480\text{V}$;
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$;
5. Essentially independent of operating temperature.



TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

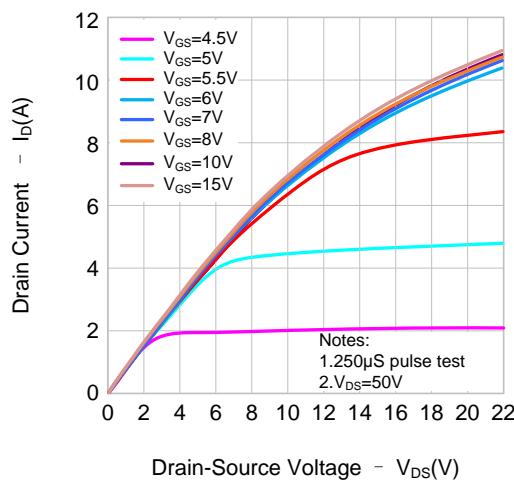


Figure 2. Transfer Characteristics

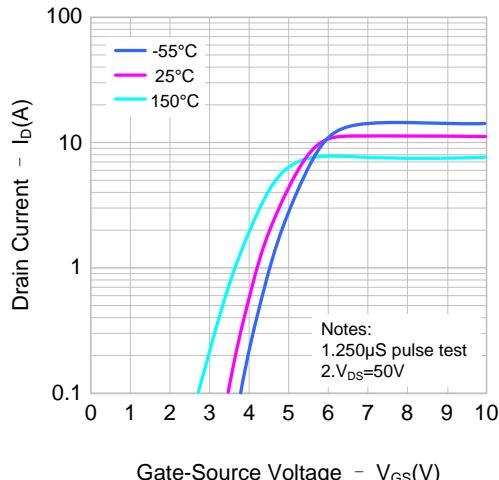


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

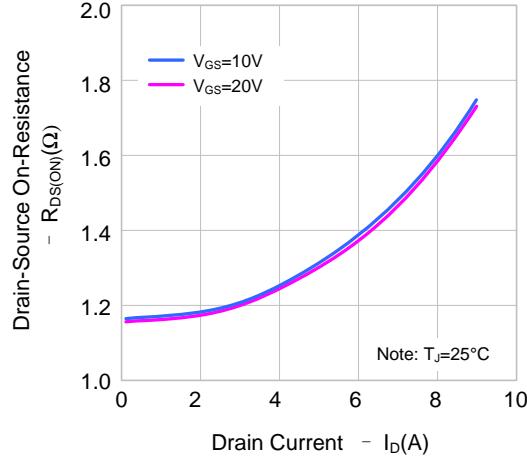


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

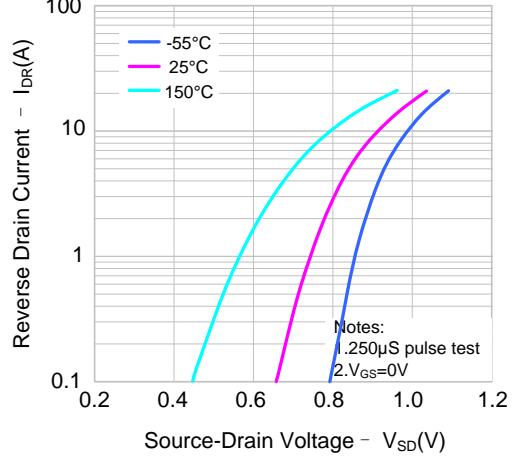


Figure 5. Capacitance Characteristics

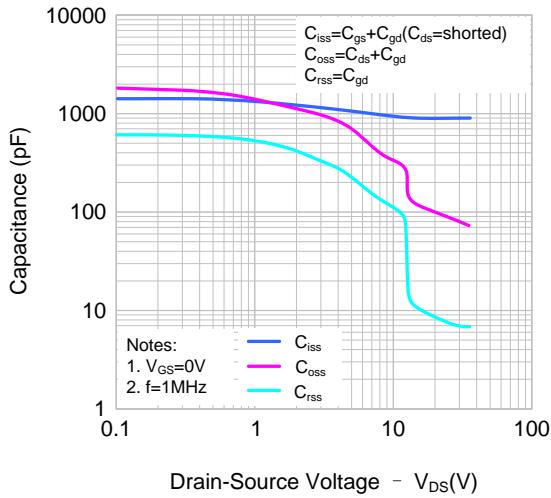
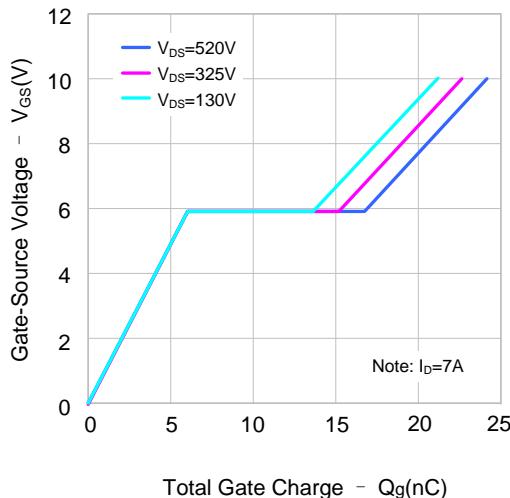


Figure 6. Gate Charge Characteristics





TYPICAL CHARACTERISTICS (CONTINUED)

Figure 7. Breakdown Voltage vs.
Temperature

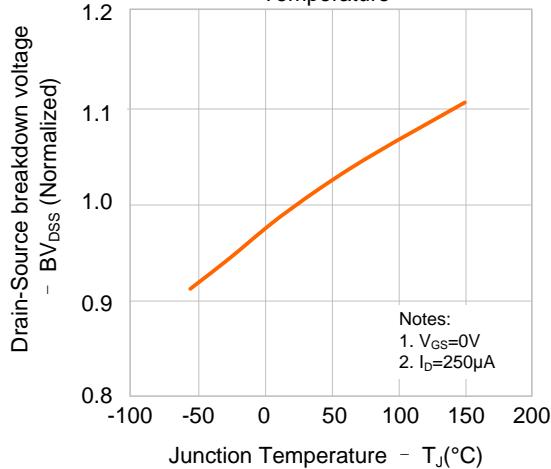


Figure 8. On-resistance Variation vs.
Temperature

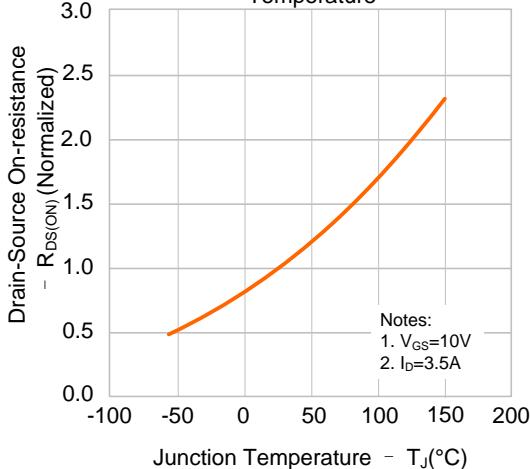


Figure 9-1. Max. Safe Operating Area
SVF7N65RD/MJ)

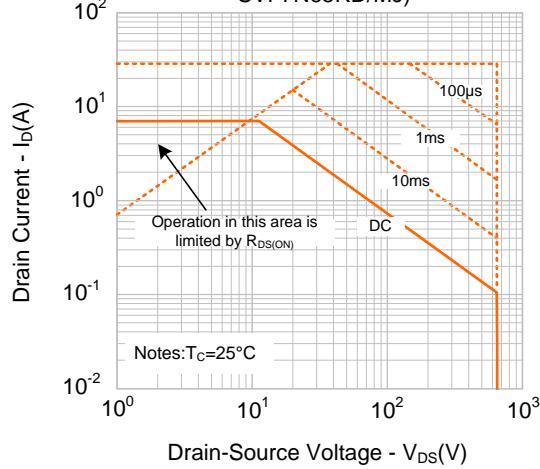


Figure 9-2. Max. Safe Operating Area
(SVF7N65RFJH/F)

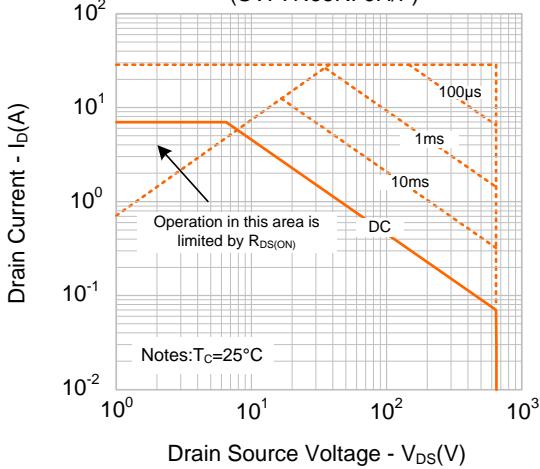
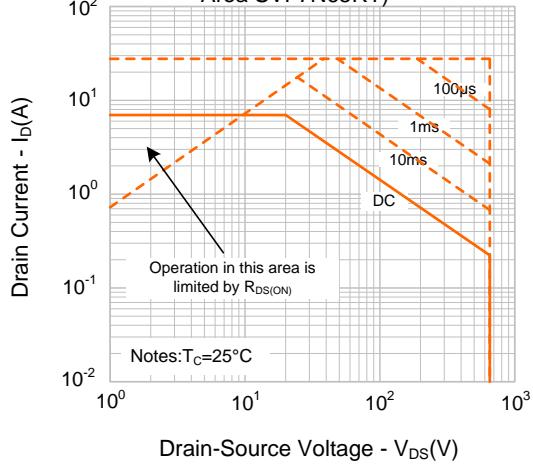


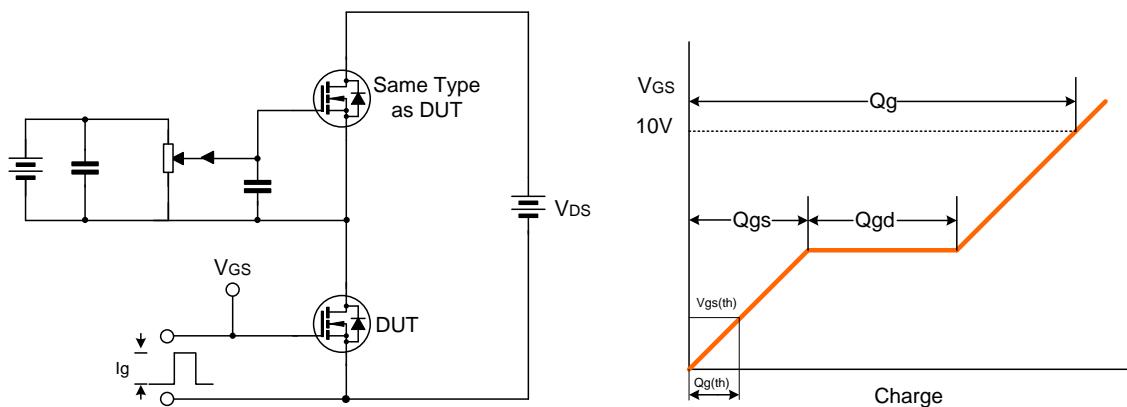
Figure 9-3. Max. Safe Operating
Area SVF7N65RT)



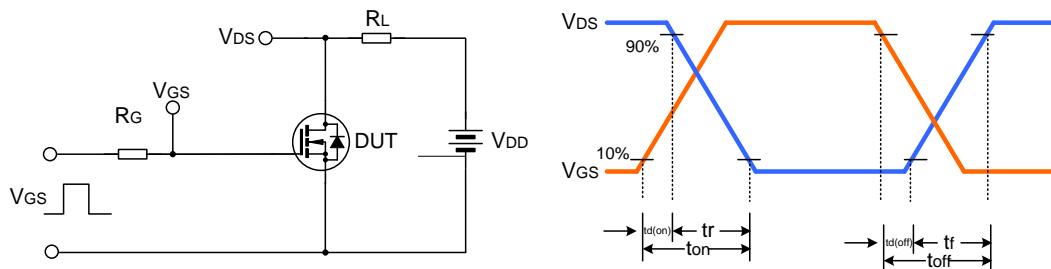


TYPICAL TEST CIRCUIT

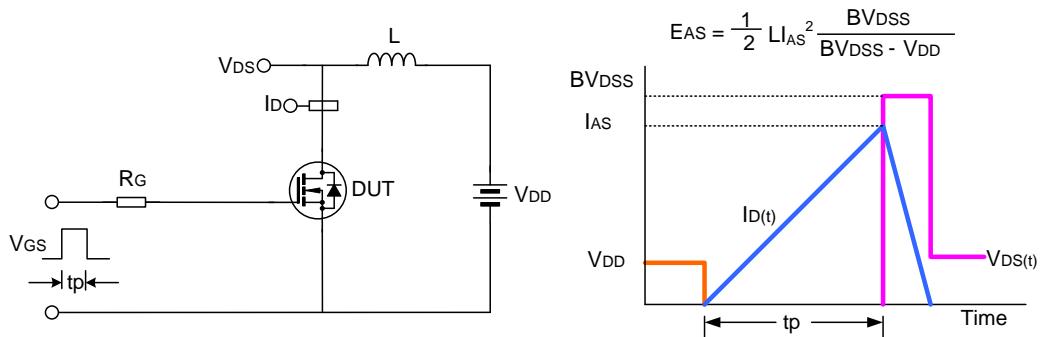
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform





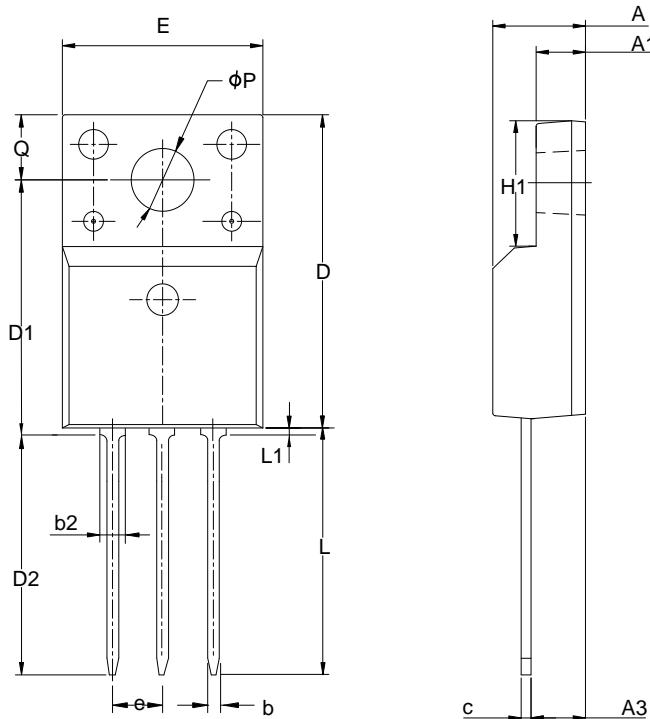
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PACKAGE OUTLINE

TO-220FJH-3L

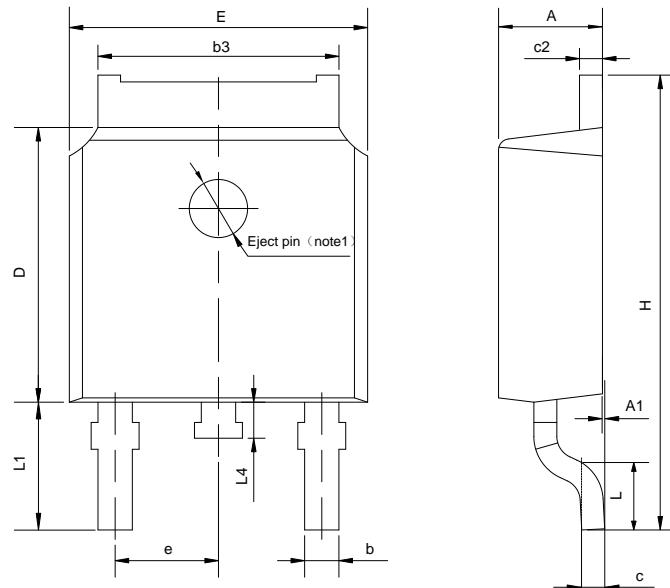
单位：毫米



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.55	0.70	0.80
b2	—	—	1.29
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	12.87	13.07	13.27
D2	12.28	12.48	12.68
E	9.73	10.16	10.36
e	2.54BCS		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	0.85
φP	3.00	3.18	3.40
Q	3.05	3.30	3.55

TO-252-2L

单位：毫米



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	—	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	—	0.65
c2	0.45	—	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

NOTE1 : There are two conditions for this position:has an eject pin or has no eject pin.



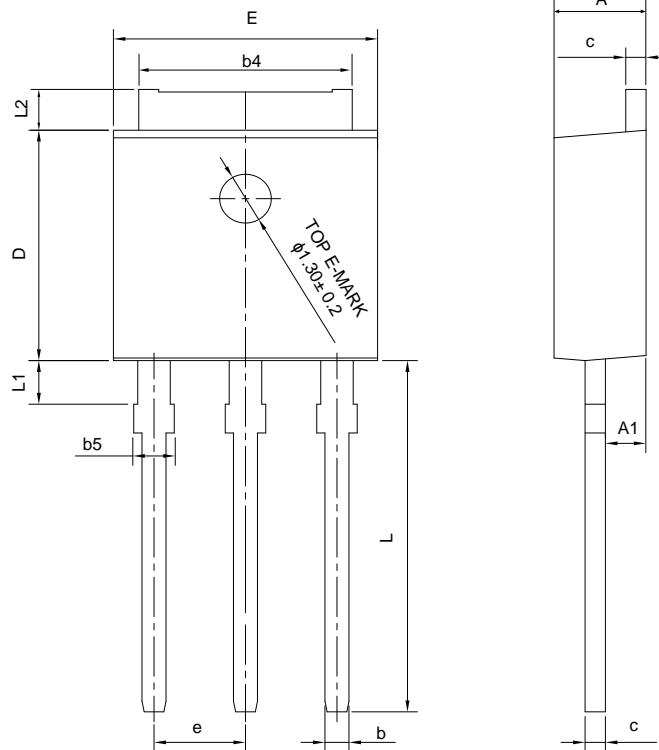
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PACKAGE OUTLINE(continued)

TO-251J-3L

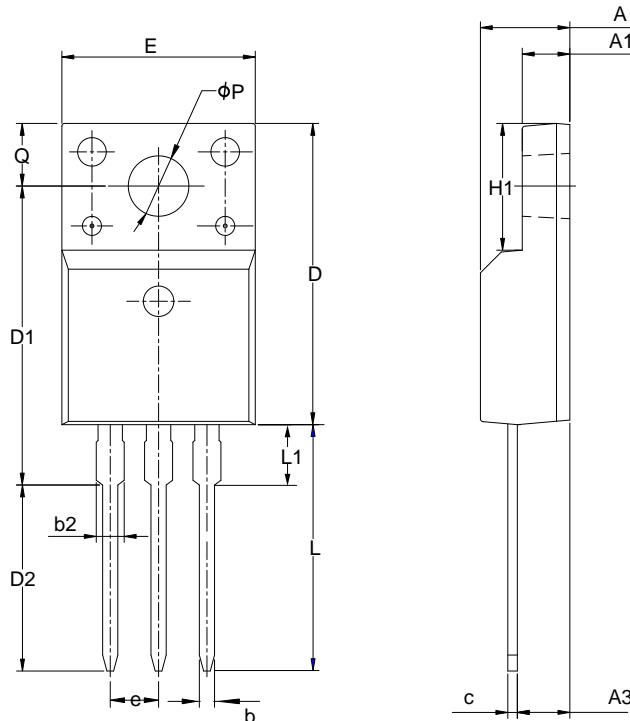
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.18	2.30	2.39
A1	0.89	1.00	1.14
b	0.56	—	0.89
b4	4.95	5.33	5.46
b5	—	—	1.05
c	0.46	—	0.61
D	5.97	6.10	6.27
E	6.35	6.60	6.73
e	2.29 BCS		
L	8.89	9.30	9.65
L1	0.95	—	1.50
L2	0.89	—	1.27

TO-220F-3L

UNIT: mm



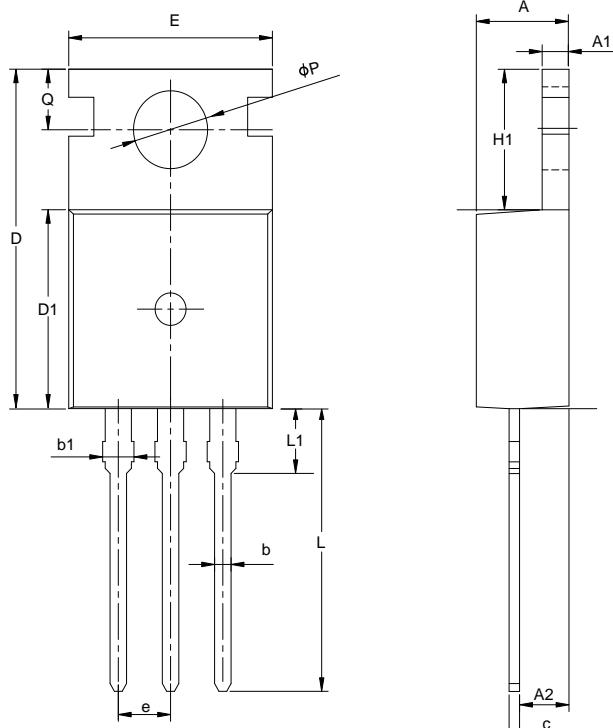
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	3.50
ØP	3.00	3.18	3.40
Q	3.05	3.30	3.55



PACKAGE OUTLINE(continued)

TO-220-3L

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	1.00	1.30	1.50
A2	1.80	2.40	2.80
b	0.60	0.80	1.00
b1	1.00	—	1.60
c	0.30	—	0.70
D	15.10	15.70	16.10
D1	8.10	9.20	10.00
E	9.60	9.90	10.40
e	2.54BSC		
H1	6.10	6.50	7.00
L	12.60	13.08	13.60
L1	—	—	3.95
ϕP	3.40	3.70	3.90
Q	2.60	—	3.20

Important notice :

- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- Our products are consumer electronic products, and / or civil electronic products.
- When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
- It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.
- When exporting, using and reselling our products, buyer must comply with the international export control laws and regulations of China, the United States, the United Kingdom, the European Union and other countries & regions.
- Product promotion is endless, our company will wholeheartedly provide customers with better products!
- Website: <http://www.silan.com.cn>



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SVF7N65RD(MJ)(FJH)(F)(T)_Datasheet

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Rev.: 1.3

Revision History:

1. Deleted NOMENCLATURE
 2. Modify Important notice
-

Rev.: 1.2

Revision History:

1. Add SVF7N65RT
 2. Update Important Notice
-

Rev.: 1.1

Revision History:

1. Delete SVF7N65RFJ
 2. Add SVF7N65RFJH
 3. Add SVF7N65RF
-

Rev.: 1.0

Revision History:

1. Preliminary
-